

RECOMMENDED PCB LAYOUT DIM'S
TOL: ±0.05 ALL

1. INTERFACE STANDARD: MIL-STD-348A;

2. MATERIAL & FINISH:

2.1 BODY: BRASS, GOLD PLATING OVER NICKEL OVER ALL;

2.2 INSULATOR: LCP-WHITE ;

2.3 CONTER CONTACT&PIN: BRASS GOLD PLATING OVER NICKEL PLATING

3. ELECTRICAL:

3.1 IMPEDANCE: 50 Ω ;

3.2 RETURN LOSS: ≥26dB DC TO 6GHz

≥20dB 6 TO 12GHz

3.3 INSERTION LOSS: ≤0.05X/(F/GHz)² dB

3.4 CENTER RESISTANCE: 6.0mΩ MAX.

3.5 OUTER RESISTANCE: 2.0mΩ MAX.

3.6 DIELECTRIC WITHSTANDING VOLTAGE 500V (AC)

4. MECHANICAL & ENVIRONMENTAL:

4.1 MECHANICAL DURABILITY: 500 CYCLES MIN.;

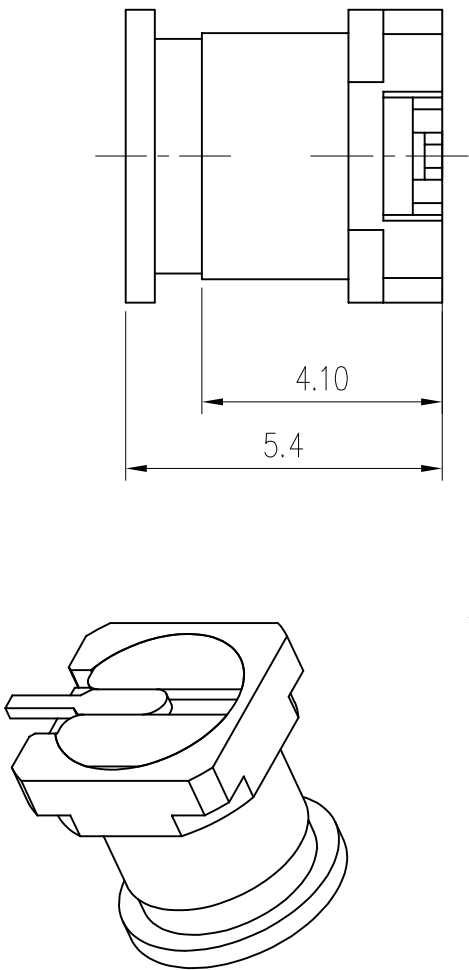
4.2 CENTER CONTACT CAPTIVATION: ≥ 7N

4.3 MAX SOLDERING 260 °C PEAK TEMPERATURE 10 SECS;

4.5 TEMPERATURE RANGE: -65 °C TO +155 °C;

5. HARMFUL MATERIAL ROHS COMPLIANCE

6. NO OXIDIZATION, SCRATCHES, CRUSH AND OIL ON SURFACES AFTER ASSEMBLY;



X.±	0.15	X.*±	S*
X.±	0.10	X.*±	
.XX±	0.05	.XX*±	
XXX±		.XXX*±	

UNITS	MM	NAME(INTENDED USE)
MATL		CUSTOMER DRAWING
SEE NOTES		PART NO.(INTENDED USE)
FINISH		KFP1204-2001-7F
SEE NOTES		APPD: L.C. Wu, May,04/2011
Q'TY		CHKD: ZH Xu, May,04/2011
		DR: Y.J. Zhang, May,04/2011

FOXCONN
HON HAI PRECISION IND. CO.,LTD.
TAPEI, TAIWAN, R.O.C.

TITLE:
SMP PULG FOR SMT RF CONN

DWG NO.:
389-0000-360

SCALE SHEET	REV.
8:1	B

REV.	EQN. NO.	APPD.
A	BC-10-0122580	L.C. Wu
B	BC-11-0047155	L.C. Wu